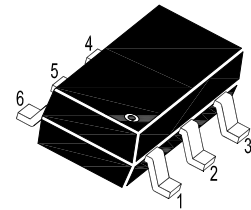
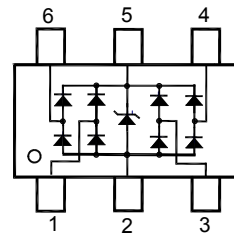


# ESDULC64DW

## ESD Protection Diode



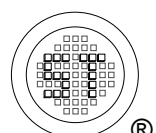
1. I/O1 2. GND 3. I/O2  
4. I/O3 5. V<sub>CC</sub> 6. I/O4  
SOT-363 Plastic Package

### Absolute Maximum Ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp = 8/20 μs)	P <sub>PK</sub>	100	W
Peak Pulse Current (tp = 8/20 μs)	I <sub>PP</sub>	6	A
IEC61000-4-2 (ESD) Air Contact	V <sub>ESD</sub>	±15 ±15	KV
Junction Temperature	T <sub>j</sub>	125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to + 150	°C

### Characteristics at T<sub>a</sub> = 25°C

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I <sub>R</sub> = 1 mA, Pin 5 to GND	V <sub>BR</sub>	6	-	V
Leakage Current at V <sub>R</sub> = 5 V	I <sub>R</sub>	-	0.5	μA
Clamping Voltage at I <sub>PP</sub> = 1 A, tp = 8/20 μs, Any I/O Pin to GND at I <sub>PP</sub> = 6 A, tp = 8/20 μs, Any I/O Pin to GND	V <sub>C</sub>	- -	12 17	V
Junction Capacitance at V <sub>R</sub> = 0 V, f = 1 MHz, Between I/O Pin to GND	C <sub>i/o-GND</sub>	-	1	pF
Junction Capacitance at V <sub>R</sub> = 0 V, f = 1 MHz, Between I/O Pins	C <sub>i/o-i/o</sub>	-	0.5	pF



# ESDULC64DW

## Electrical Characteristic Curves

Fig 1. Pulse Waveform

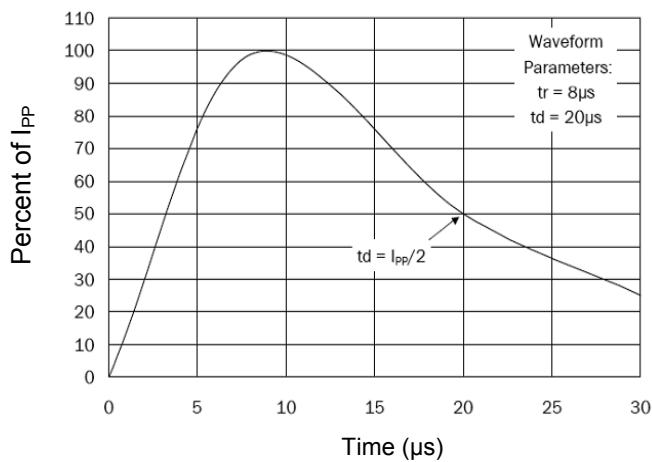


Fig 2. Power Derating Curve

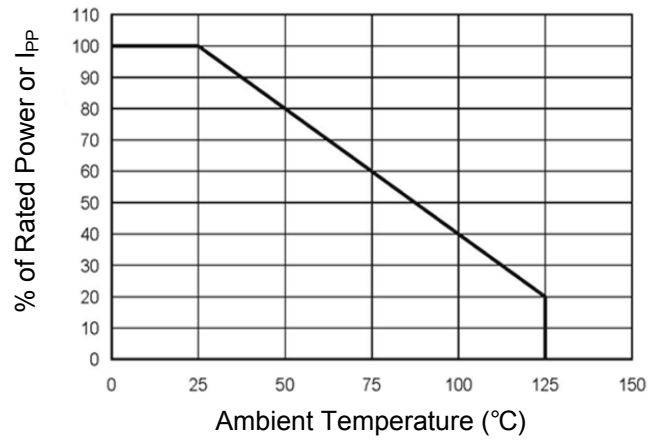


Fig 3. Clamping Voltage Curve

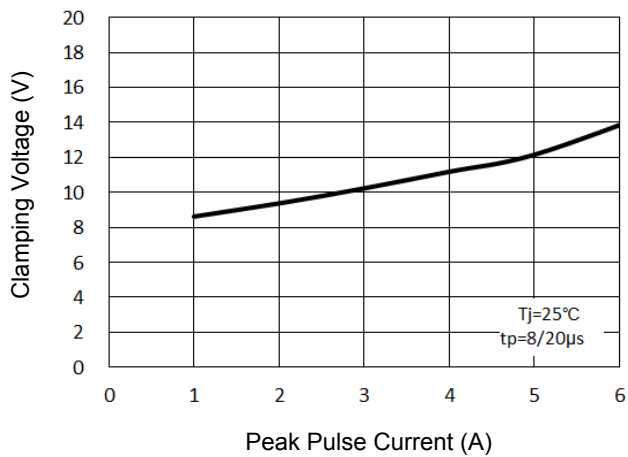


Fig 4. Junction Capacitance

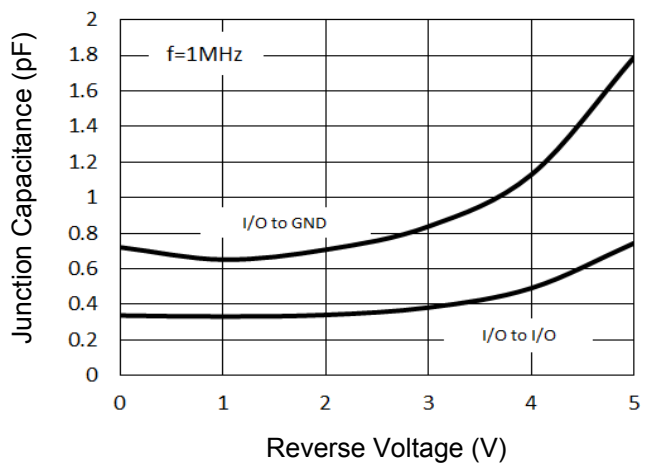
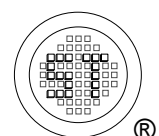
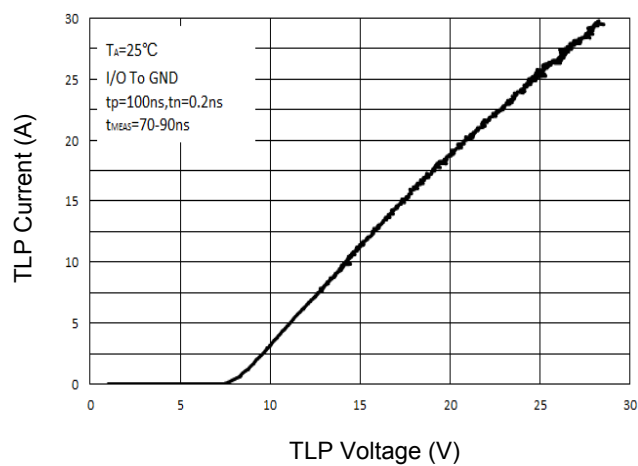
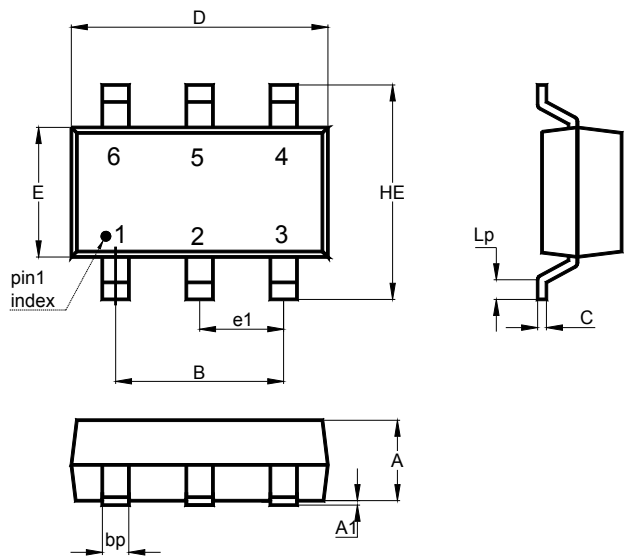


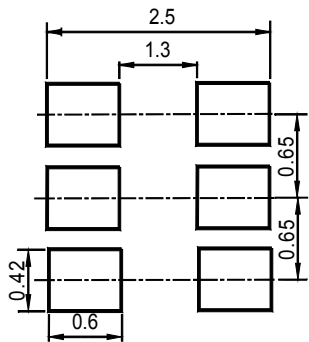
Fig. 5 TLP Curve





Unit	A	A1	B	C	D	E	e1	HE	Lp	bp
mm	1.0 0.9	0.1 0	1.3 typ.	0.25 0.1	2.2 1.8	1.35 1.15	0.65 typ.	2.2 2.0	0.4 0.15	0.3 0.1

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-363	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" TF " = Part No.  
 " YM " = Date Code Marking  
 " Y " = Year  
 " M " = Month  
 Font type: Arial

